

said insulative inorganic filler being contained in an amount of from 10 to 200 parts by weight based on 100 parts by weight of the adhesive resin composition.

B1
Amended

2. (Twice Amended) An adhesive for bonding circuit members according to claim 1, said adhesive further comprising a second adhesive layer containing an adhesive resin composition as a main ingredient.

3. (Twice Amended) An adhesive for bonding circuit members according to claim 1, said adhesive further comprising a second adhesive layer containing an adhesive resin composition as a main ingredient and having a modulus of elasticity of from 100 to 2,000 MPa at 40°C after curing.

Please add the following new claim to the application:

B2

--32. An adhesive for bonding circuit members according to claim 1, consisting of said first adhesive layer.--
